

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Seung Don LEE	07/27/2010
Hyun Ju KIM	07/27/2010
Hyoung Won KIM	07/27/2010
RECEIVING PARTY DATA	
Name:	LG Electronics Inc.
Street Address:	20 Yeouido-dong Yeongdeungpo-gu
City:	Seoul
State/Country:	REPUBLIC OF KOREA
Postal Code:	150-721
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	29367293
CORRESPONDENCE DATA	
Fax Number:	(202)739-3001
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Email:	patents@morganlewis.com
Correspondent Name:	Robert J. Gaybrick
Address Line 1:	1111 Pennsylvania Ave, NW
Address Line 4:	Washington, DISTRICT OF COLUMBIA 20004
ATTORNEY DOCKET NUMBER:	0010882-7015
NAME OF SUBMITTER:	Robert J. Goodell
Total Attachments: 2 source=001082-7015_Assignment_08052010#page1.tif source=001082-7015_Assignment_08052010#page2.tif	

CH \$40.00 29367293

501254435

PATENT
REEL: 024797 FRAME: 0154

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

MOBILE PHONE

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on ___, (Application No. ___); and

WHEREAS, LG ELECTRONICS INC., a corporation of Republic of Korea, whose post office address is 20 Yeouido-dong Yeongdeungpo-gu Seoul 150-721 Republic of Korea, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. 29/367,293, filed August 5, 2010) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of Sole or First Assignor LEE, Seung Don	Assignor's Signature <i>Lee, Seung Don</i>	Date July 27, 2010
Address Wanggung Apt. 5-406, Ichon-1-dong, Yongsan-gu, Seoul, Korea		Citizenship Republic of Korea
Full Name of Second Assignor KIM, Hyun Ju	Assignor's Signature <i>Kim, Hyun Ju</i>	Date July 27, 2010
Address Shingu Bless Valley 102-805, Bangi-1-dong 197, Songpa-gu, Seoul, Korea		Citizenship Republic of Korea
Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

Full Name of Third Assignor KIM, Hyoung Won	Assignor's Signature <i>Kim, Hyoung Won</i>	Date July 27, 2010
Address Samsung Raemian Apt. 205-1304, Singongdeok-dong, Mapo-gu, Seoul, Korea		Citizenship Republic of Korea
Full Name of Fourth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Fifth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Sixth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Seventh Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Eighth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Ninth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Tenth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Eleventh Assignor	Assignor's Signature	Date
Address		Citizenship
Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		